

Electronic Acknowledgement Receipt

EFS ID:	1444397
Application Number:	10594322
International Application Number:	
Confirmation Number:	3313
Title of Invention:	Epoxy resin composition for the encapsulation of semiconductors and semiconductor devices
First Named Inventor/Applicant Name:	Daisuke Hirokane
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Filer Authorized By:	Marvin Jay Spivak
Attorney Docket Number:	295408US40PCT
Receipt Date:	17-JAN-2007
Filing Date:	
Time Stamp:	14:45:42
Application Type:	U.S. National Stage under 35 USC 371

Payment information:

Submitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part /.zip	Pages (if appl.)
1	Oath or Declaration filed	295408usDeclaration.pdf	578602	no	3

Warnings:

Information:	
Total Files Size (in bytes):	578602
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